Special Issue

Emerging Non-Destructive Testing Technologies: Advances and Applications

Message from the Guest Editors

The Special Issue on "Thermographic Nondestructive Testing: Advances and Applications" is dedicated to the most recent developments and practical applications of thermographic techniques in non-destructive testing (NDT). Thermographic NDT employs infrared imaging to detect and analyse the thermal properties of materials and structures, thereby providing a powerful tool for identifying, characterising and quantifying defects and ensuring quality without causing damage. Recent advancements in thermographic NDT have led to significant improvements in the accuracy, efficiency, and versatility of these methods. This issue covers a range of key topics, including innovations in infrared camera technology, enhanced data processing algorithms, and novel applications across various industries such as aerospace, civil engineering, and manufacturing.

Guest Editors

Dr. Ester D’Accardi

Dr. Rosa De Finis

Prof. Dr. Umberto Galietti

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Applied Sciences
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
applsci@mdpi.com

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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32,
20133 Milano, Italy

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